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First Named Invent r	Datta, Madhav
Gr up Art Unit	2814
Examiner Name	Pham, Long

Sheet 1 of 1

Attorney Docket No: 884.522US1

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Substitute Disclosure Statement Form (PTO-1449)
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Form 1449*	Atty. Docket No.: 884.522US1	Serial No. Unknown
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)	Applicant: Madhav Datta et al.	
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